

THE UNIVERSITY OF CHICAGO

A thermal conductive tape article is provided which is adhered to the surface of an integrated circuit device to dissipate heat from the device. The thermal conductive tape article is preferably corrugated and may have a number of configurations providing an expanded surface area. The corrugated tape article may also have a metal strip bonded to one or both sides of the tape article to form a single-faced or double-faced corrugated tape article. The tape article is preferably made of copper or aluminum.